ABSTRACT

A method of manufacturing a semiconductor chip having no cut deformed layer and chipping and having a sufficiently high transverse strength, comprising the steps of, when dividing a semiconductor wafer W formed so that a plurality of circuits are divided by streets on a surface into semiconductor chips for each circuit, forming cut grooves 19a not leading from the rear surfaces to the front surfaces of the streets so that uncut parts 20 are formed on the front surface side of the semiconductor wafer W and applying etching thereto from the rear surface side to edge the rear surface, side faces of the cut grooves, and uncut parts 20, whereby the wafer can be divided into the semiconductor chips.



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